## NLAST4501

## Single SPST Analog Switch

The NLAST4501 is an analog switch manufactured in sub-micron silicon-gate CMOS technology. It achieves very low $\mathrm{R}_{\mathrm{ON}}$ while maintaining extremely low power dissipation. The device is a bilateral switch suitable for switching either analog or digital signals, which may vary from zero to full supply voltage.

The NLAST4501 is a low voltage, TTL (low threshold) compatible device, pin for pin compatible with the MAX4501.

The Enable pin is compatible with standard TTL level outputs when supply voltage is nominal 5.0 V . It is also over-voltage tolerant, making it a very useful logic level translator.

## Features

- Guaranteed $\mathrm{R}_{\mathrm{ON}}$ of $32 \Omega$ at 5.5 V
- Low Power Dissipation: $\mathrm{I}_{\mathrm{CC}}=2 \mu \mathrm{~A}$
- Low Threshold Enable pin TTL compatible at 5.0 V
- TTL version and pin for pin with NLAS4501
- Provides Voltage translation for many different voltage levels
3.3 to 5.0 V , Enable pin may go as high as +5.5 V
1.8 to 3.3 V
1.8 to 2.5 V
- Improved version of MAX4501 (at any voltage between 2 and 5.5 V )
- Chip Complexity: FETs = 11
- $\mathrm{Pb}-$ Free Packages are Available


Figure 1. Pinout (Top View)

ON Semiconductor ${ }^{\circledR}$
http://onsemi.com
SC70-5/SC-88A/SOT-353
DF SUFFIX
CASE 419A

FUNCTION TABLE

| On/Off Enable Input | State of Analog Switch |
| :---: | :---: |
| L | Off |
| H | On |

## ORDERING INFORMATION

See detailed ordering and shipping information on page 8 of this data sheet.

MAXIMUM RATINGS

| Rating | Symbol | Value | Unit |
| :---: | :---: | :---: | :---: |
| Positive DC Supply Voltage | $\mathrm{V}_{\mathrm{CC}}$ | -0.5 to +7.0 | V |
| Digital Input Voltage (Enable) | $\mathrm{V}_{\text {IN }}$ | -0.5 to +7.0 | V |
| Analog Output Voltage ( $\mathrm{V}_{\mathrm{NO}}$ or $\mathrm{V}_{\mathrm{COM}}$ ) | $\mathrm{V}_{\text {IS }}$ | -0.5 to $\mathrm{V}_{C C}+0.5$ | V |
| DC Current, Into or Out of Any Pin | $\mathrm{I}_{\mathrm{K}}$ | $\pm 20$ | mA |
| Storage Temperature Range | $\mathrm{T}_{\text {STG }}$ | -65 to +150 | ${ }^{\circ} \mathrm{C}$ |
| Lead Temperature, 1 mm from Case for 10 Seconds | $\mathrm{T}_{\mathrm{L}}$ | 260 | ${ }^{\circ} \mathrm{C}$ |
| Junction Temperature under Bias | $\mathrm{T}_{\mathrm{J}}$ | + 150 | ${ }^{\circ} \mathrm{C}$ |
| Thermal Resistance SC70-5/SC-88A (Note 1) <br> TSOP-5  | $\theta_{\mathrm{JA}}$ | $\begin{aligned} & 350 \\ & 230 \end{aligned}$ | ${ }^{\circ} \mathrm{C} / \mathrm{W}$ |
| Power Dissipation in Still Air at $85^{\circ} \mathrm{C} \quad$ SC70-5/SC-88A | $\mathrm{P}_{\mathrm{D}}$ | $\begin{aligned} & 150 \\ & 200 \end{aligned}$ | mW |
| Moisture Sensitivity | MSL | Level 1 |  |
| Flammability Rating Oxygen Index: 30\% - 35\% | $\mathrm{F}_{\mathrm{R}}$ | UL 94 V-0 @ 0.125 in |  |
| ESD Withstand VoltageHuman Body Model (Note 2) <br> Machine Model (Note 3) <br> Charged Device Model (Note 4) | $\mathrm{V}_{\text {ESD }}$ | $\begin{gathered} >2000 \\ >100 \\ N / A \end{gathered}$ | V |
| Latchup Performance $\quad$ Above $\mathrm{V}_{\mathrm{CC}}$ and Below GND at $85^{\circ} \mathrm{C}$ (Note 5) | ILatchup | $\pm 300$ | mA |

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. Measured with minimum pad spacing on an FR4 board, using 10 mm -by-1 inch, 2-ounce copper trace with no air flow.
2. Tested to EIA/JESD22-A114-A.
3. Tested to EIA/JESD22-A115-A.
4. Tested to JESD22-C101-A.
5. Tested to EIA/JESD78.

## RECOMMENDED OPERATING CONDITIONS

| Parameter | Symbol | Min | Max | Unit |
| :--- | :---: | :---: | :---: | :---: |
| Positive DC Supply Voltage | $\mathrm{V}_{\mathrm{CC}}$ | 2.0 | 5.5 | V |
| Digital Input Voltage (Enable) | $\mathrm{V}_{\mathrm{IN}}$ | GND | 5.5 | V |
| Static or Dynamic Voltage Across an Off Switch | $\mathrm{V}_{\mathrm{IO}}$ | GND | $\mathrm{V}_{\mathrm{CC}}$ | V |
| Analog Input Voltage (NO, COM) | $\mathrm{V}_{\mathrm{IS}}$ | GND | $\mathrm{V}_{\mathrm{CC}}$ | V |
| Operating Temperature Range, All Package Types | $\mathrm{T}_{\mathrm{A}}$ | -55 | +125 | ${ }^{\circ} \mathrm{C}$ |
| Input Rise or Fall Time, <br> (Enable Input) | ( |  |  |  |

## DEVICE JUNCTION TEMPERATURE VERSUS TIME TO 0.1\% BOND FAILURES

| Junction <br> Temperature ${ }^{\circ} \mathbf{C}$ | Time, Hours | Time, Years |
| :---: | :---: | :---: |
| 80 | $1,032,200$ | 117.8 |
| 90 | 419,300 | 47.9 |
| 100 | 178,700 | 20.4 |
| 110 | 79,600 | 9.4 |
| 120 | 37,000 | 4.2 |
| 130 | 17,800 | 2.0 |
| 140 | 8,900 | 1.0 |



Figure 2. Failure Rate vs. Time Junction Temperature

DC CHARACTERISTICS - Digital Section (Voltages Referenced to GND)

| Parameter | Condition | Symbol | $\mathrm{V}_{\mathrm{cc}}$ | Guaranteed Max Limit |  |  | Unit |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  |  | $-55^{\circ} \mathrm{C}$ to $25^{\circ} \mathrm{C}$ | $<85^{\circ} \mathrm{C}$ | $<125^{\circ} \mathrm{C}$ |  |
| Minimum High-Level Input Voltage, Enable Inputs |  | $\mathrm{V}_{\mathrm{IH}}$ | $\begin{aligned} & 3.0 \\ & 4.5 \\ & 5.5 \end{aligned}$ | $\begin{aligned} & 1.4 \\ & 2.0 \\ & 2.0 \end{aligned}$ | $\begin{aligned} & 1.4 \\ & 2.0 \\ & 2.0 \end{aligned}$ | $\begin{aligned} & 1.4 \\ & 2.0 \\ & 2.0 \end{aligned}$ | V |
| Maximum Low-Level Input Voltage, Enable Inputs |  | $\mathrm{V}_{\text {IL }}$ | $\begin{aligned} & 3.0 \\ & 4.5 \\ & 5.5 \end{aligned}$ | $\begin{gathered} 0.53 \\ 0.8 \\ 0.8 \end{gathered}$ | $\begin{gathered} 0.53 \\ 0.8 \\ 0.8 \end{gathered}$ | $\begin{gathered} 0.53 \\ 0.8 \\ 0.8 \end{gathered}$ | V |
| Maximum Input Leakage Current, Enable Inputs | $\mathrm{V}_{\mathrm{IN}}=5.5 \mathrm{~V}$ or GND | IN | 0 V to 5.5 V | $\pm 0.1$ | $\pm 1.0$ | $\pm 1.0$ | $\mu \mathrm{A}$ |
| Maximum Quiescent Supply Current (per package) | Enable and VIS = V ${ }_{\text {CC }}$ or GND | ICC | 5.5 | 1.0 | 1.0 | 2.0 | $\mu \mathrm{A}$ |

DC ELECTRICAL CHARACTERISTICS - Analog Section

| Parameter | Condition | Symbol | $\mathrm{V}_{\text {cc }}$ | Guaranteed Max Limit |  |  | Unit |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  |  | $-55^{\circ} \mathrm{C}$ to $25^{\circ} \mathrm{C}$ | $<85{ }^{\circ} \mathrm{C}$ | $<125^{\circ} \mathrm{C}$ |  |
| Maximum ON Resistance (Figures 8-12) | $\begin{aligned} & \hline V_{I N}=V_{I H} \\ & V_{S I}=V_{\mathrm{CC}} \text { to GND } \\ & \mathrm{I}_{I S} \mathrm{I}=\leq 10.0 \mathrm{~mA} \end{aligned}$ | RoN | $\begin{aligned} & \hline 3.0 \\ & 4.5 \\ & 5.5 \end{aligned}$ | $\begin{aligned} & 45 \\ & 30 \\ & 25 \end{aligned}$ | $\begin{aligned} & 50 \\ & 35 \\ & 30 \end{aligned}$ | $\begin{aligned} & 55 \\ & 40 \\ & 35 \end{aligned}$ | $\Omega$ |
| ON Resistance Flatness | $\begin{aligned} & \mathrm{V}_{I \mathrm{~N}}=\mathrm{V}_{1 \mathrm{H}} \\ & \mathrm{I}_{\mathrm{IS}} \mid=\leq 10.0 \mathrm{~mA} \\ & \mathrm{~V}_{I S}=1 \mathrm{~V}, 2 \mathrm{~V}, 3.5 \mathrm{~V} \end{aligned}$ | $\mathrm{R}_{\text {FLAT(ON) }}$ | 4.5 | 4 | 4 | 5 | $\Omega$ |
| Off Leakage Current, Pin 2 (Figure 3) | $\begin{aligned} & \mathrm{V}_{\mathrm{IN}}=\mathrm{V}_{\mathrm{IL}} \\ & \mathrm{~V}_{\mathrm{NO}}=1.0 \mathrm{~V}, \mathrm{~V}_{\mathrm{COM}}=4.5 \mathrm{~V} \text { or } \\ & \mathrm{V}_{\mathrm{COM}}=1.0 \mathrm{~V} \text { and } \mathrm{V}_{\mathrm{NO}} 4.5 \mathrm{~V} \end{aligned}$ | $\mathrm{I}_{\text {NO(OFF) }}$ | 5.5 | 1 | 10 | 100 | nA |
| Off Leakage Current, Pin 1 (Figure 3) | $\begin{array}{\|l} \hline \mathrm{V}_{\mathrm{IN}}=\mathrm{V}_{\mathrm{IL}} \\ \mathrm{~V}_{\mathrm{NO}}=4.5 \mathrm{~V} \text { or } 1.0 \mathrm{~V} \\ \mathrm{~V}_{\mathrm{COM}}=1.0 \mathrm{~V} \text { or } 4.5 \mathrm{~V} \end{array}$ | $\mathrm{I}_{\text {Com(OFF) }}$ | 5.5 | 1 | 10 | 100 | nA |

AC ELECTRICAL CHARACTERISTICS (Input $t_{r}=t_{f}=3.0 \mathrm{~ns}$ )


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ADDITIONAL APPLICATION CHARACTERISTICS (Voltages Referenced to GND Unless Noted)

| Parameter | Condition | Symbol | $\begin{gathered} \mathrm{v}_{\mathrm{cc}} \\ \mathrm{~V} \end{gathered}$ | $\begin{aligned} & \text { Limit } \\ & 25^{\circ} \mathrm{C} \end{aligned}$ | Unit |
| :---: | :---: | :---: | :---: | :---: | :---: |
| Maximum On-Channel -3dB Bandwidth or Minimum Frequency Response | $\mathrm{V}_{\text {IS }}=0 \mathrm{dBm}$ <br> $\mathrm{V}_{\text {IS }}$ centered between $\mathrm{V}_{\mathrm{CC}}$ and $G N D$ <br> (Figures 6 and 14) | BW | $\begin{aligned} & \hline 3.0 \\ & 4.5 \\ & 5.5 \end{aligned}$ | $\begin{aligned} & \hline 190 \\ & 200 \\ & 220 \end{aligned}$ | MHz |
| Maximum Feedthrough On Loss | $\mathrm{V}_{\text {IS }}=0 \mathrm{dBm} @ 10 \mathrm{kHz}$ <br> $\mathrm{V}_{\text {IS }}$ centered between $\mathrm{V}_{\mathrm{CC}}$ and $G N D$ <br> (Figure 6) | V ONL | $\begin{aligned} & 3.0 \\ & 4.5 \\ & 5.5 \end{aligned}$ | $\begin{aligned} & -2 \\ & -2 \\ & -2 \end{aligned}$ | dB |
| Off-Channel Isolation | $\mathrm{f}=100 \mathrm{kHz} ; \mathrm{V}_{\mathrm{IS}}=1 \mathrm{VRMS}$ <br> $\mathrm{V}_{\text {IS }}$ centered between $\mathrm{V}_{\mathrm{CC}}$ and GND <br> (Figures 6 and 15) | $\mathrm{V}_{\text {ISO }}$ | $\begin{aligned} & 3.0 \\ & 4.5 \\ & 5.5 \end{aligned}$ | -93 | dB |
| Charge Injection <br> Enable Input to Common I/O | $\begin{aligned} & \mathrm{V}_{I S}=\mathrm{V}_{\mathrm{CC}} \text { to } \mathrm{GND}, \mathrm{~F}_{I S}=20 \mathrm{kHz} \\ & \mathrm{t}_{\mathrm{r}_{2}}=\mathrm{t}_{f}=3 \mathrm{~ns} \\ & \mathrm{R}_{I S}=0 \Omega, C_{L}=1000 \mathrm{pF} \\ & Q=C_{L}{ }^{*} \Delta \mathrm{~V}_{\mathrm{OUT}} \\ & \text { (Figures } 7 \text { and 16) } \end{aligned}$ | Q | $\begin{aligned} & \hline 3.0 \\ & 5.5 \end{aligned}$ | $\begin{aligned} & 1.5 \\ & 3.0 \end{aligned}$ | pC |
| Total Harmonic Distortion THD + Noise | $\begin{array}{r} \mathrm{F}_{\mathrm{IS}}=20 \mathrm{~Hz} \text { to } 1 \mathrm{MHz}, \mathrm{R}_{\mathrm{L}}=\text { Rgen }=600 \Omega, \mathrm{C}_{\mathrm{L}}=50 \mathrm{pF} \\ \mathrm{~V}_{\mathrm{IS}}=3.0 \mathrm{~V}_{\mathrm{PP}} \text { sine wave } \\ \mathrm{V}_{\text {IS }}=5.0 \mathrm{~V}_{\mathrm{PP}} \text { sine wave } \end{array}$ <br> (Figure 17) | THD | $\begin{aligned} & 3.3 \\ & 5.5 \end{aligned}$ | $\begin{gathered} \hline 0.3 \\ 0.15 \end{gathered}$ | \% |



Figure 3. Switch Leakage vs. Temperature

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Figure 4. $\mathrm{t}_{\mathrm{ON}} / \mathrm{t}_{\mathrm{OFF}}$


Figure 5. $\mathrm{t}_{\mathrm{ON}} / \mathrm{t}_{\mathrm{OFF}}$

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Channel switch control/s test socket is normalized. Off isolation is measured across an off channel. On loss is the bandwidth of an On switch. $\mathrm{V}_{\text {ISO }}$, Bandwidth and $\mathrm{V}_{\text {ONL }}$ are independent of the input signal direction.
$\mathrm{V}_{\text {ISO }}=$ Off Channel Isolation $=20$ Log $\left(\frac{\mathrm{V}_{\text {OUT }}}{\mathrm{V}_{\text {IN }}}\right)$ for $\mathrm{V}_{\text {IN }}$ at 100 kHz
$\mathrm{V}_{\text {ONL }}=$ On Channel Loss $=20 \log \left(\frac{\mathrm{~V}_{\text {OUT }}}{\mathrm{V}_{\text {IN }}}\right)$ for $\mathrm{V}_{\text {IN }}$ at 100 kHz to 50 MHz
Bandwidth $(B W)=$ the frequency 3 dB below $\mathrm{V}_{\mathrm{ONL}}$

Figure 6. Off Channel Isolation/On Channel Loss (BW)/Crosstalk (On Channel to Off Channel)/V ${ }_{\text {ONL }}$


Figure 7. Charge Injection: (Q)


Figure 8. Ron vs. $\mathrm{V}_{\text {com }}$ and $\mathrm{V}_{\mathrm{CC}}\left(@ 25^{\circ} \mathrm{C}\right)$


Figure 10. R $\mathrm{R}_{\mathrm{ON}}$ vs. $\mathrm{V}_{\mathrm{COM}}$ and Temperature, $\mathrm{V}_{\mathrm{cc}}=2.5 \mathrm{~V}$


Figure 12. $\mathrm{R}_{\mathrm{ON}}$ vs. $\mathrm{V}_{\text {COM }}$ and Temperature, $\mathrm{V}_{\mathrm{CC}}=4.5 \mathrm{~V}$


Figure 9. $\mathrm{R}_{\mathrm{ON}}$ vs. $\mathrm{V}_{\text {COM }}$ and Temperature, $\mathrm{V}_{\mathrm{cc}}=2.0 \mathrm{~V}$


Figure 11. R $\mathrm{R}_{\mathrm{ON}}$ vs. $\mathrm{V}_{\mathrm{COM}}$ and Temperature, $\mathrm{V}_{\mathrm{CC}}=3.0 \mathrm{~V}$


Figure 13. Switching Time vs. Supply Voltage, $\mathrm{T}=25^{\circ} \mathrm{C}$

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Figure 14. ON Channel Bandwidth and Phase Shift Over Frequency


Figure 15. Off Channel Isolation


Figure 16. Charge Injection vs. $\mathbf{V}_{\text {COM }}$


Figure 17. THD vs. Frequency

ORDERING INFORMATION

| Device | Device Nomenclature |  |  |  |  | Package | Shipping ${ }^{\dagger}$ |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  | Circuit Indicator | Technology | Device Function | Package Suffix | Tape \& Reel Suffix |  |  |
| NLAST4501DFT2 | NL | AST | 4501 | DF | T2 | $\begin{gathered} \hline \text { SC-88A/SOT-353/ } \\ \text { SC70 } \end{gathered}$ | 3000/Tape \& Reel |
| NLAST4501DFT2G |  |  |  |  |  | $\begin{gathered} \hline \text { SC-88A/SOT-353/ } \\ \text { SC70 } \\ \text { (Pb-Free) } \end{gathered}$ |  |
| NLAST4501DTT1 |  |  |  | DT | T1 | TSOP-5 |  |
| NLAST4501DTT1G |  |  |  |  |  | $\begin{aligned} & \text { TSOP-5 } \\ & \text { (Pb-Free) } \end{aligned}$ |  |

[^0]

SOLDER FOOTPRINT


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
CONTROLLING DIMENSION: INCH.
2. 419A-01 OBSOLETE. NEW STANDARD

419A-02.
DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

|  | INCHES |  | MILIMETERS |  |  |
| :---: | :---: | :---: | :---: | :---: | :---: |
| DIM | MIN | MAX | MIN | MAX |  |
| A | 0.071 | 0.087 | 1.80 | 2.20 |  |
| B | 0.045 | 0.053 | 1.15 | 1.35 |  |
| C | 0.031 | 0.043 | 0.80 | 1.10 |  |
| D | 0.004 | 0.012 | 0.10 | 0.30 |  |
| G | 0.026 BSC | 0.65 BSC |  |  |  |
| H | - |  | 0.004 | --1 |  |
| J | 0.004 | 0.010 | 0.10 | 0.25 |  |
| K | 0.004 | 0.012 | 0.10 | 0.30 |  |
| N | 0.008 |  | REF | 0.20 REF |  |
| S | 0.079 | 0.087 | 2.00 |  |  |

GENERIC MARKING
DIAGRAM*


XXX = Specific Device Code
M = Date Code

- = Pb-Free Package
(Note: Microdot may be in either location)
*This information is generic. Please refer to device data sheet for actual part marking. $\mathrm{Pb}-$ Free indicator, " G " or microdot " -r ", may or may not be present. Some products may not follow the Generic Marking.

| STYLE 1: | STYLE 2: | STYLE 3: |
| :--- | :--- | :--- |
| PIN 1. BASE | PIN 1. ANODE | PIN 1. ANODE 1 |
| 2. EMITTER | 2. EMITTER | 2. N/C |
| 3. BASE | 3. BASE | 3. ANODE 2 |
| 4. COLLECTOR | 4. COLLECTOR | 4. CATHODE 2 |
| 5. COLLECTOR | 5. CATHODE | 5. CATHODE 1 |
|  |  |  |
| STYLE 6: | STYLE 7: | STYLE 8: |
| PIN 1. EMITTER 2 | PIN 1. BASE | PIN 1. CATHODE |
| 2. BASE 2 | 2. EMITTER | 2. COLLECTOR |
| 3. EMITTER 1 | 3. BASE | 3. N/C |
| 4. COLLECTOR | 4. COLLECTOR | 4. BASE |
| 5. COLLECTOR 2/BASE 1 | 5. COLLECTOR | 5. EMITTER |

## STYLE 4: <br> STYLE 5:

## PIN 1. SOURCE 1

2. DRAIN $1 / 2$
3. SOURCE 1
4. GATE 1
5. GATE 2

## STYLE 9

PIN 1. ANODE
2. CATHODE
3. ANODE
4. ANODE
5. ANODE

PIN 1. CATHODE
2. COMMON ANODE
2. COMTHODE 2
4. CATHODE 3
5. CATHODE 4

Note: Please refer to datasheet for style callout. If style type is not called out in the datasheet refer to the device datasheet pinout or pin assignment.

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| ---: | :--- | :--- | :--- |
| DESCRIPTION: | SC-88A (SC-70-5/SOT-353) | PAGE 1 OF 1 |

[^1]NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH

THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS A AND B DO NOT INCLUDE MOLD

FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE. DIMENSION A.
5. OPTIONAL CONSTRUCTION: AN ADDITIONAL

TRIMMED LEAD IS ALLOWED IN THIS LOCATION TRIMMED LEAD NOT TO EXTEND MORE THAN 0.2 FROM BODY.

| DIM | MILLIMETERS |  |
| :---: | :---: | :---: |
|  | MIN | MAX |
| A | 2.85 | 3.15 |
| B | 1.35 | 1.65 |
| C | 0.90 | 1.10 |
| $\mathbf{D}$ | 0.25 | 0.50 |
| $\mathbf{G}$ | 0.95 | BSC |
| $\mathbf{H}$ | 0.01 | 0.10 |
| $\mathbf{J}$ | 0.10 | 0.26 |
| $\mathbf{K}$ | 0.20 | 0.60 |
| $\mathbf{M}$ | $0^{\circ}$ | $10^{\circ}$ |
| $\mathbf{S}$ | 2.50 | 3.00 |

GENERIC MARKING DIAGRAM*

Analog

XXX = Specific Device Code
A = Assembly Location
= Specific Device Code
M = Date Code
$\mathrm{Y}=$ Year $\quad$ = Pb-Free Package
W = Work Week

- = Pb-Free Package
(Note: Microdot may be in either location)
*This information is generic. Please refer to device data sheet for actual part marking. $\mathrm{Pb}-F r e e$ indicator, " G " or microdot " $\mathrm{\bullet}$ ", may or may not be present.
*For additional information on our $\mathrm{Pb}-$ Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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| ---: | :--- | :--- | :--- |
| DESCRIPTION: | TSOP-5 | PAGE 1 OF 1 |

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FSA3051TMX NLAS4684FCTCG NLAS5223BLMNR2G NLX2G66DMUTCG 425541DB 425528R 099044FB NLAS5123MNR2G PI5A4157CEX NLAS4717EPFCT1G PI5A3167CCEX SLAS3158MNR2G PI5A392AQE PI5A4157ZUEX PI5A3166TAEX FSA634UCX XS3A1T3157GMX TC4066BP(N,F) DG302BDJ-E3 PI5A100QEX HV2605FG-G HV2301FG-G RS2117YUTQK10 RS2118YUTQK10 RS2227XUTQK10 ADG452BRZ-REEL7 MAX4066ESD+ MAX391CPE+ MAX4730EXT+T MAX314CPE+ BU4066BCFV-E2 MAX313CPE+ BU4S66G2-TR NLASB3157MTR2G TS3A4751PWR NLAST4599DFT2G NLAST4599DTT1G DG300BDJ-E3 DG2503DB-T2-GE1 TC4W53FU(TE12L,F) HV2201FG-G 74HC2G66DC. 125 DG3257DN-T1-GE4 ADG619BRMZ-REEL ADG1611BRUZ-REEL7 DG2535EDQ-T1-GE3 LTC201ACN\#PBF 74LV4066DB,118 ISL43410IUZ FSA2275AUMX


[^0]:    $\dagger$ For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

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